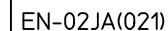
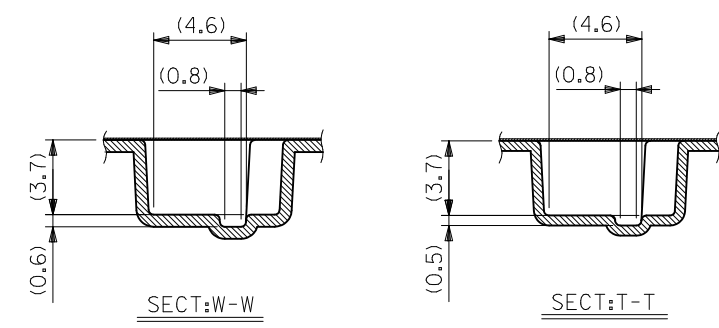
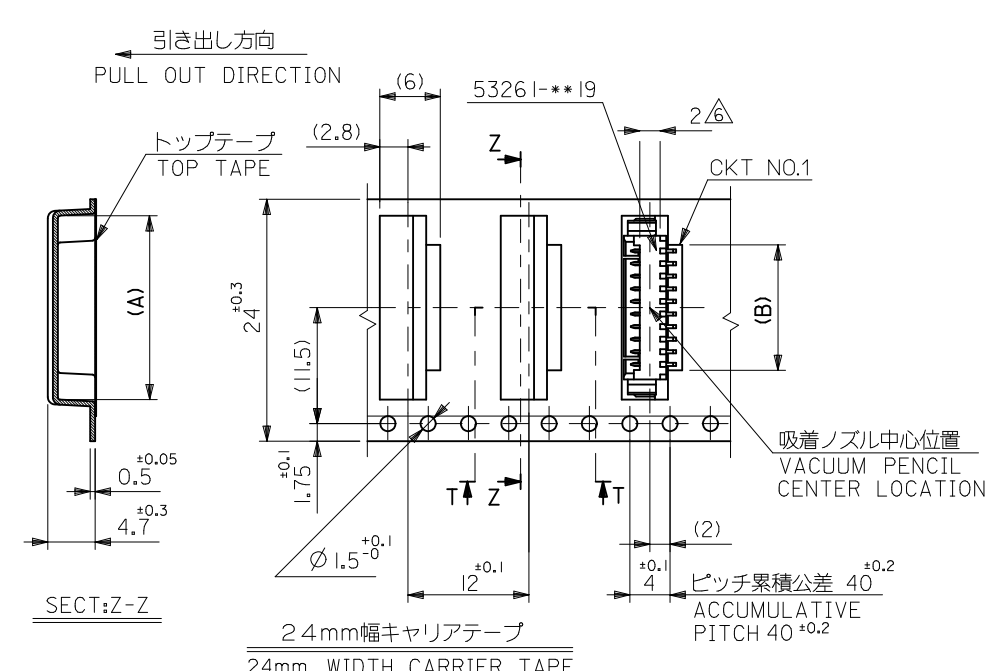
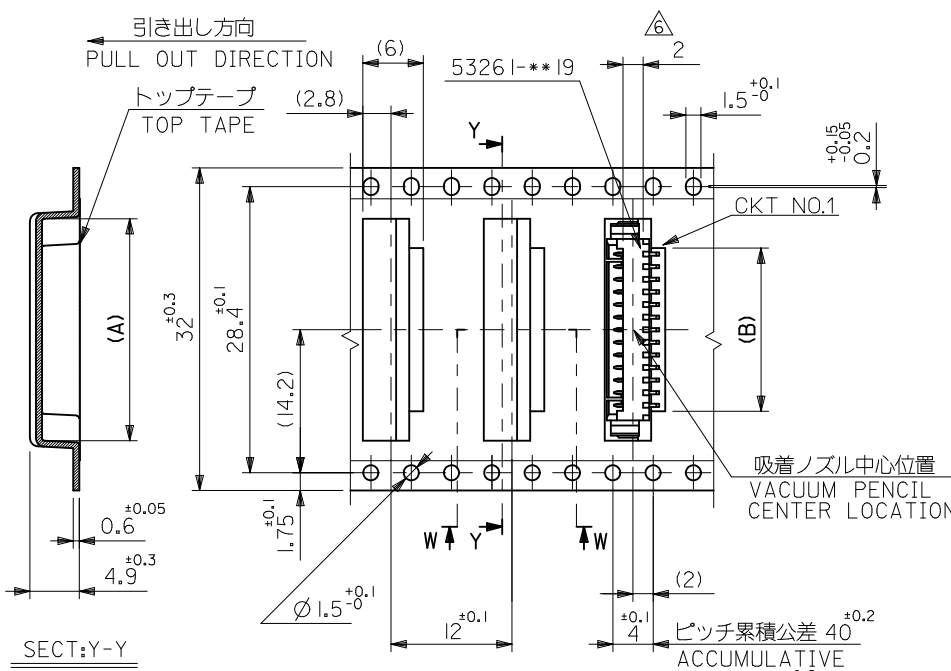


53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRWN:YAOYAGI 2006/02/02 CHKD:YMAEDA 2006/02/03 APPR:NUKITA 2006/02/07 REV 0	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± ---	Y.AOYAGI	2006/01/30	TITLE 1.25 W-TO-B CONN. 51021,53261 MATING CROSS SECTION				
		10 OVER 30 UNDER	± ---	Y.MAEDA	2006/01/30					
		30 OVER	± ---	N.UKITA	2006/01/30	MOLEX INCORPORATED				
		ANGULAR ±--- °		MATERIAL NO.		DOCUMENT NO.		SHEET NO.		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE CHART		SD-51021-002		1 OF 1		
	REV	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION								





32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
			13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSD TAPE PACKAGE	極数 CKT.
					オーダー番号 ORDER NO.	

REVISED	EC NO: 2010/02/17	DRWN:YGO10	CHKD:KASAKAWA	APPR:	DESCRIPTION	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
						10 UNDER ± 0.2	H. SHIMABUKUR DATE '04/02/06	TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
						10 OVER 30 UNDER ± 0.25	CHECKED BY DATE '04/02/06				
						30 OVER ± 0.3	APPROVED BY DATE 2010/02/18	MOLEX INCORPORATED			
						ANGULAR ±3 °	MATERIAL NO.				
						DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE & SHEET 1.3		SD-53261-023	
REV	D	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

10

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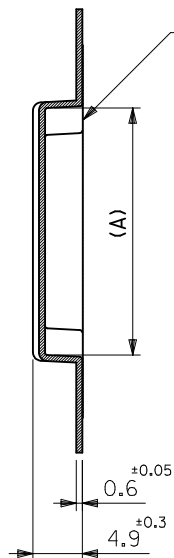
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2

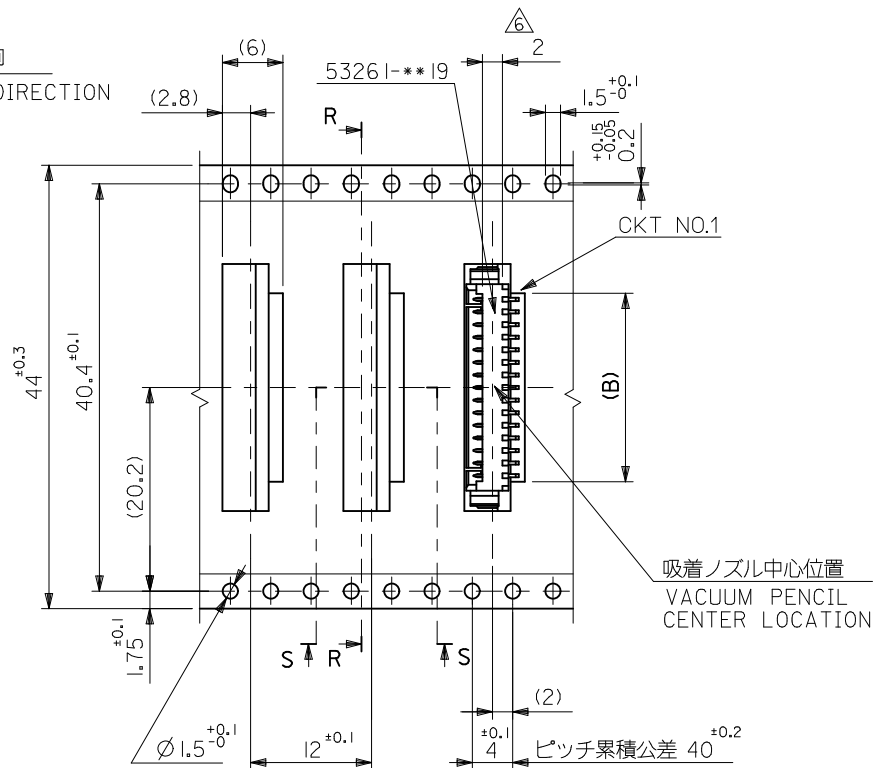
1

引き出し方向  
PULL OUT DIRECTION

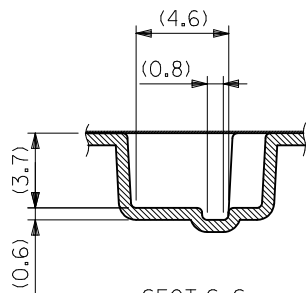
トップテープ  
TOP TAPE



SECT:R-R



44mm幅キャリアテープ  
44mm WIDTH CARRIER TAPE



SECT:S-S

MODEL NO. 53261-\*\*\*71

REVISED  
EC NO:  
D  
DRWN:Y.GOTO  
CHKD:KASAKAWA  
APPR:  
REV

DESCRIPTION  
2010/02/17

GENERAL TOLERANCES  
(UNLESS SPECIFIED)

10 UNDER	± 0.2
10 OVER 30 UNDER	± 0.25
30 OVER	± 0.3
ANGULAR	± 3 °
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	

DIMENSION STYLE  
MM ONLY

DRAWN BY H. SHIMABUKUR	DATE '04/02/06
CHECKED BY K. TOJO	DATE '04/02/06
APPROVED BY NUKITA	DATE 2010/02/18
MATERIAL NO. SEE TABLE & SHEET 12	
SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

SCALE  
---

DESIGN UNITS  
METRIC

THIRD ANGLE  
PROJECTION

TITLE  
1.25 W/B CONN WAFER ASSY  
FOR SMT EMBSTP PKG

MOLEX INCORPORATED

DOCUMENT NO.  
SD-53261-023

SHEET NO.  
3 OF 3

44	49.4	45.4	18.7	24.5	53261-1571	I5
			17.45	23.25	53261-1471	I4
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSSED TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.

9

8

7

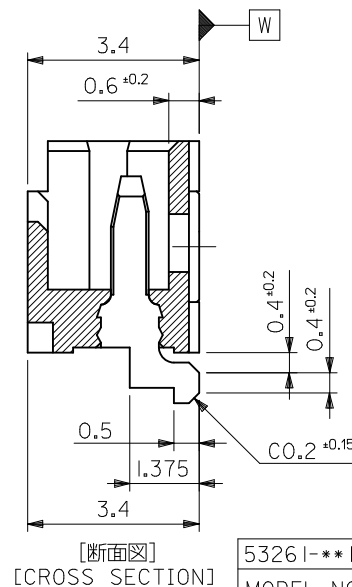
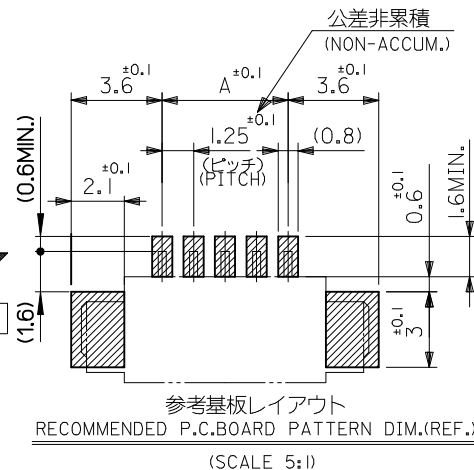
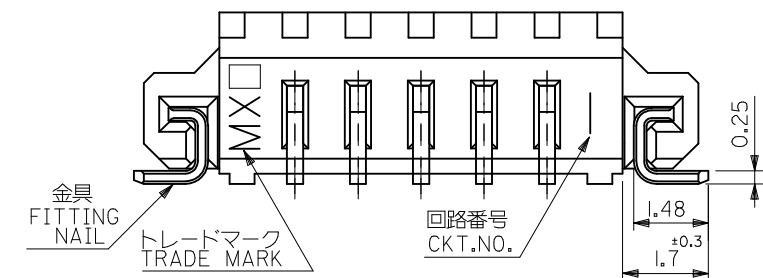
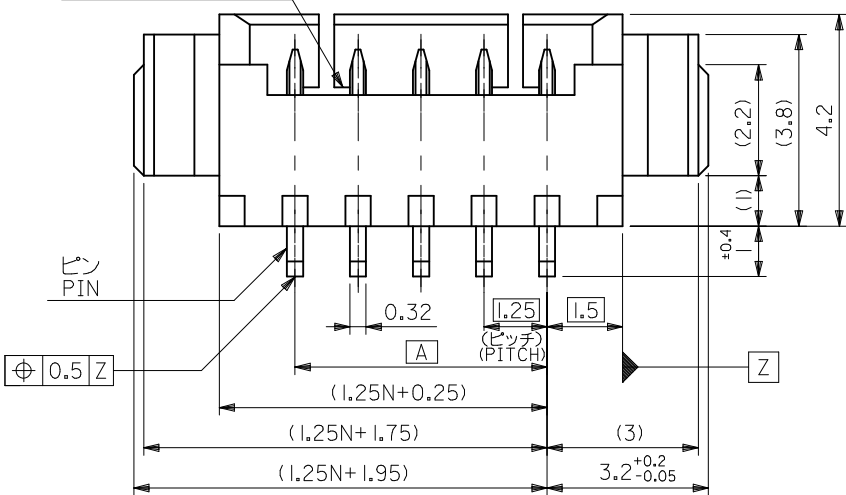
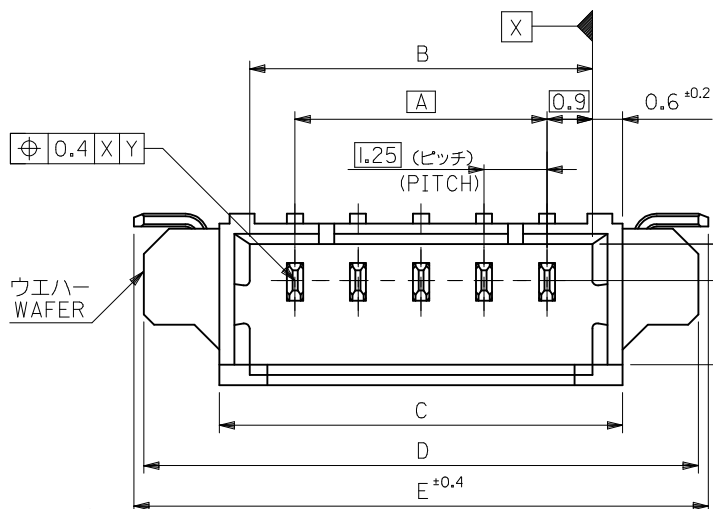
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

























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2



#### 注記 NOTES

1. 嵌合相手: 51021 シリウス  
MATES WITH: 51021 SERIES
2. 材質 MATERIAL  
ウエハー: NYLON46, UL94V-0  
ピン: リン青銅  
: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM  
金具: リン青銅  
FITTING NAIL: PHOS-BRO  
: 銅メッキ 1.0 マイクロメートル以上  
: TIN 1.0 MICROMETER MINIMUM  
: ニッケル下地 1.0 マイクロメートル以上  
: NICKEL (UNDER PLATING) 1.0 MICROMETER MINIMUM
3. ロック窓は2、3極は1箇所、4極以上は2箇所とする。  
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
4. ソリダーテール部のスレ量及び金具(補強板)のスレ量は基準面 W に対し、上方向 0.05MAX.、下方向に 0.1 MAX. とする。  
OFFSET BETWEEN BASIS PLANE W TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:  
UPPER SIDE: 0.05MAX.  
LOWER SIDE: 0.1MAX.
5. 本製品は 53261-\*\*-10 の鉛フリー品である。  
THIS PRODUCT IS LEAD FREE OF 53261-\*\*-10
6. ELV 及び RoHS 適合品  
ELV AND RoHS COMPLIANT.
7. ソルダーテール及び金具の平坦度は 0.1 以下。  
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

26.4	26	23	21.8	20	53261-1771	53261-1719	17	
23.9	23.5	20.5	19.3	17.5	 -1571	 -1519	15	
22.65	22.25	19.25	18.05	16.25	 -1471	 -1419	14	
21.4	21	18	16.8	15	 -1371	 -1319	13	
20.15	19.75	16.75	15.55	13.75	 -1271	 -1219	12	
18.9	18.5	15.5	14.3	12.5	 -1171	 -1119	11	
17.65	17.25	14.25	13.05	11.25	 -1071	 -1019	10	
16.4	16	13	11.8	10	 -0971	 -0919	9	
15.15	14.75	11.75	10.55	8.75	 -0871	 -0819	8	
13.9	13.5	10.5	9.3	7.5	 -0771	 -0719	7	
12.65	12.25	9.25	8.05	6.25	 -0671	 -0619	6	
11.4	11	8	6.8	5	 -0571	 -0519	5	
10.15	9.75	6.75	5.55	3.75	 -0471	 -0419	4	
8.9	8.5	5.5	4.3	2.5	 -0371	 -0319	3	
19	7.65	7.25	4.25	3.05	1.25	53261-0271	53261-0219	2
D.	E	D	C	B	A	EMBOSSED TAPE PKG ORDER No.	MATERIAL. NO.	極數 CKT.

REVISED EC NO: J2016-1122 DRWN:QHE31 CHKD:SAKIYAMA APPR:KANEKO	DESCRIPTION J REV	GENERAL TOLERANCES (UNLESS SPECIFIED)			DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	 THIRD ANGLE PROJECTION	
		0.25 UNDER	UNDER	± 0.03	DRAWN BY	DATE	TITLE  1.25 WIRE TO BOARD WAFER ASS FOR SMT			
		0.25 OVER	0.5 UNDER	± 0.05	HSHIMABU	04/02/06				
		0.5 OVER	1.0 UNDER	± 0.1	CHECKED BY	DATE				
		1.0 OVER	10 UNDER	± 0.2	KTOJO	04/02/06				
		10 OVER	30 UNDER	± 0.25	APPROVED BY	DATE	molex			
		30 OVER		± 0.3	MSASAO	04/02/06				
		ANGULAR ±3 °			MATERIAL NO.			DOCUMENT NO.		SHEET NO.
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			SEE CHART		SD-53261-024			1 OF 1
					THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					